



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC061N08NS5		<b>Issued</b>		10. August 2018		
<b>MA#</b>		MA002290876						
<b>Package</b>		PG-TDSON-8-7		<b>Weight*</b>		118.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.714	0.60	0.60	6029	6029
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		319	
	non noble metal	copper	7440-50-8	37.762	31.92	31.96	319063	319478
	noble metal	gold	7440-57-5	0.045	0.04	0.04	378	378
wire	organic material	carbon black	1333-86-4	0.087	0.07		734	
encapsulation	plastics	epoxy resin	-	6.865	5.80		58008	
	inorganic material	silicondioxide	60676-86-0	36.500	30.84	36.71	308399	367141
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12265	12265
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1399	1399
solder	non noble metal	tin	7440-31-5	0.021	0.02		179	
	noble metal	silver	7440-22-4	0.026	0.02		224	
	non noble metal	lead	7439-92-1	1.011	0.85	0.89	8540	8943
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.56	9.57	95647	95772
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
	non noble metal	copper	7440-50-8	22.292	18.83	18.86	188349	188595
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com